



US 20240179866A1

(19) **United States**

(12) **Patent Application Publication**
SHI et al.

(10) **Pub. No.: US 2024/0179866 A1**

(43) **Pub. Date: May 30, 2024**

(54) **TEMPERATURE ADAPTIVE INFORMATION HANDLING SYSTEM**

Publication Classification

(71) Applicant: **Dell Products L.P.**, Round Rock, TX (US)

(51) **Int. Cl.**
H05K 7/20 (2006.01)
G06F 1/20 (2006.01)
H01L 23/38 (2006.01)

(72) Inventors: **Zhuo Ya SHI**, Beijing (CN); **Xin Zhi MA**, Shanghai (CN)

(52) **U.S. Cl.**
CPC **H05K 7/20145** (2013.01); **G06F 1/206** (2013.01); **H01L 23/38** (2013.01); **H05K 7/20209** (2013.01)

(73) Assignee: **Dell Products L.P.**, Round Rock, TX (US)

(57) **ABSTRACT**

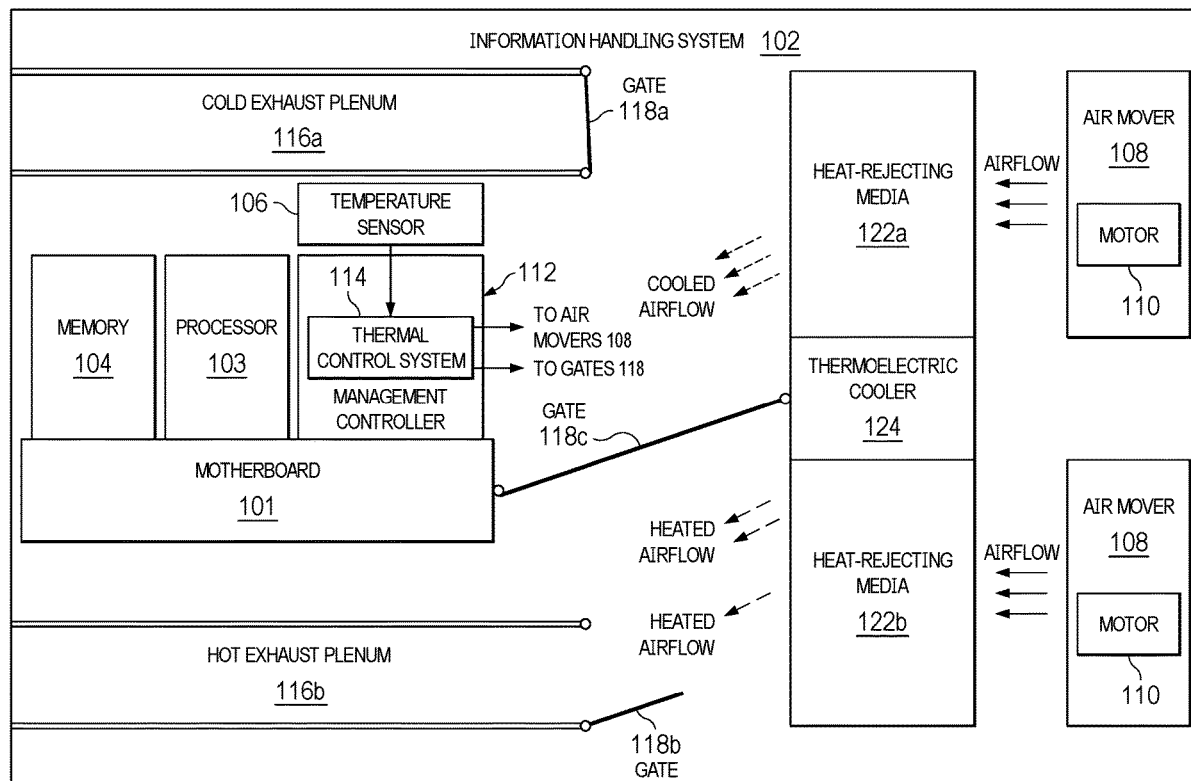
In an information handling system, positions of a plurality of mechanical structures may be configured to be controlled to selectively direct airflow cooled by first heat-rejecting media and a thermoelectric cooler between flowing through the first exhaust plenum and flowing proximate to the one or more information handling resources and selectively direct airflow heated by the second heat-rejecting media and the thermoelectric cooler between flowing through the second exhaust plenum and flowing proximate to the one or more information handling resources.

(21) Appl. No.: **18/171,466**

(22) Filed: **Feb. 20, 2023**

(30) **Foreign Application Priority Data**

Nov. 24, 2022 (CN) 202211497591.9



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